



## FOR IMMEDIATE RELEASE

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# DISCO Selects Plasma-Therm as Global Business Partner for Plasma Dicing Technology

TOKYO and ST. PETERSBURG, Fla. (May 31, 2016) — DISCO Corporation, the world's largest dicing equipment provider, has signed a global distribution agreement with Plasma-Therm for its plasma dicing technology, the companies announced today.

The quality and cost-saving benefits of plasma dicing will now be available to semiconductor manufacturing customers worldwide through DISCO Corp.'s global sales and service network.

DISCO executive Noboru Yoshinaga said, "DISCO is keenly aware that plasma dicing is a key enabling technology for advanced packaging, and now we can provide complete Kiru, Kezuru, Migaku (dicing, grinding, polishing) solutions to customers. After a careful evaluation, DISCO determined that Plasma-Therm's technology is the solution of choice, due to its cost of ownership and performance," he said.

DISCO will install a 300 mm Singulator® system in its Tokyo facility this year to support customer demonstrations and semiconductor device packaging evaluations.

Abdul Lateef, Plasma-Therm CEO, said, "We are extremely pleased to be partnering with DISCO, the recognized leader in back-end processing. The industry needs the enabling technology of plasma dicing to overcome today's semiconductor advanced packaging challenges — small and sensitive devices and thin wafers."

Plasma-Therm has been granted multiple patents for its inventions related to equipment and applications for plasma dicing on tape. Plasma-Therm shipped its first Singulator® plasma dicing system in early 2013. Customers in Europe, Asia, and the United States have been using Singulator® systems in production since then, and have reported up to 30 percent higher die yield per wafer.

— MORE —

For more information about plasma dicing and Singulator® systems, visit [www.plasmatherm.com](http://www.plasmatherm.com) and [www.disco.co.jp](http://www.disco.co.jp)

### **About DISCO Corporation**

Established in 1937, DISCO is a global leader in the fields of advanced *Kiru* (cutting), *Kezuru* (grinding), and *Migaku* (polishing) technologies used in manufacturing of semiconductors and electrical components. Along with electronic devices, such as PCs, smartphones and wearables, DISCO's cutting edge technologies also support the evolution of automobiles, medical applications and other products used in our everyday lives.

### **About Plasma-Therm**

Established in 1974, Plasma-Therm is a U.S. manufacturer of advanced plasma processing equipment, focusing on research and development to high-volume production in specialty semiconductor markets, including advanced packaging, wireless communication, photonics, solid-state lighting, MEMS/NEMS, nanotechnology, renewable energy, data storage, photomask, and R&D. Plasma-Therm offers leading etching and deposition technologies and solutions for these markets. Sales and service locations throughout North America, Europe and Asia-Pacific meet the diverse needs of Plasma-Therm's global customer base. Please visit [www.plasmatherm.com](http://www.plasmatherm.com) for more information.

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